

# Customer Process Change Notification Form PCN-2010-412

## Part Information

Cirrus Logic Part # / Quantity

CS3308-CQZ CS5346-CQZ CS3318-CQZ CS42324-CQZ CS4245-CQZ CS42325-CQZ CS5345-CQZ

PCN Effective Date:

Lot Effective Date:

Cirrus P/N Change:  Yes  No

(Contact the sales representative for availability of samples if applicable)

If yes, provide new part number:

Package Mark Change:  Yes  No

If Yes, briefly explain:

The assembly identifier will change from WA to BA. xxWAxxxxxyww to xxBAxxxxxyww Country of origin will change from Taiwan to China.

*[Any Fab, Assembly, or Design changes results in pack mark changes, please provide detail]*

**Reason for Change:**

- |  |  |
|--|--|
| <input type="checkbox"/> Design/New Rev  | <input type="checkbox"/> Fab Process                           |
| <input type="checkbox"/> Assembly Site   | <input checked="" type="checkbox"/> Additional Assembly Source |
| <input type="checkbox"/> Fab Site        | <input type="checkbox"/> Assembly Process                      |
| <input type="checkbox"/> Other (Specify) | <input type="checkbox"/> Additional Fab Source                 |

**Description of Change:**

- |   |  |
|---|--|
| <input type="checkbox"/> Fix Errata                 | <input type="checkbox"/> Yield Enhancement       |
| <input type="checkbox"/> Fix Known Bug              | <input type="checkbox"/> Performance Improvement |
| <input checked="" type="checkbox"/> Other (specify) |  |

Addition of assembly site SCC. Summary of Bill of Material Change: 48 LQFP Current - SPIL New Site - SCC Mold Compound Sumitomo G700 No Change Die Attach Sumitomo 1033BF Ablebond 3230 Wire 0.8 mil Au No Change Leadframe 0.205" x 0.205" 0.180" x 0.180" 0.160" x 0.160" 0.157" x 0.157" Finish Matte Sn, 100% No Change

**Quality and Reliability Impact:**

Qualification Data Required?  Yes  No

**Reliability Report: QRR091013**

**Subject/Purpose:**

This is to qualify the Bill Of Materials change at STATSChipPAC (China) for the Pb-free 48 and 64 lead LQFP packages to Sumitomo G700 mold compound and Ablebond 3230 epoxy by similarity.

**APPROVALS:**

\_\_\_\_\_  
Rod Boutwell  
Reliability Engineering

**Results:**

Qualification successful.

**STATUS:**

Complete - Pass

<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results (Fail/Sample)</u>
Precondition MSL-3	24HR 125 °C Bake	JESD22-A113	Precondition	1	0/154
QJ1842 (Similarity)	192HR 30°C/60%RH Soak		Precondition	2	0/22
QJ1851	3 pass 260 °C Convection		Precondition	3	0/231
QJ1843 (Similarity)	reflow		Precondition	4	0/22
QJ1844 (Similarity)			Precondition	5	0/22
QJ1845 (Similarity)			Precondition	6	0/77
QJ1846 (Similarity)			Precondition	7	0/22
QJ1847 (Similarity)			Precondition	8	0/231
QJ1848 (Similarity)			Precondition	9	0/22
QJ1849 (Similarity)			Precondition	10	0/231
QJ1850					

**Background Information:**

Part #: CX5375      Rev: G      Fab: Chartered      Lead Finish: Pb-free  
 Package: 64LQFP      Assembly: STATSChipPAC (China)

<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results (Fail/sample)</u>
THB	85 °C	JESD22-A101	1000 Hours	1	0/77
QJ1794 (Similarity)	85 %RH		1000 Hours	2	0/77
QJ1795 (Similarity)	5.25 Volts		1000 Hours	3	0/77
QJ1808	Static		1000 Hours	3	0/77
	85 °C				
	85 %RH				
	5.0 Volts				
	Static				
Temperature Cycle cond. C	-65 °C	JESD22-A104	500 Cycles	1	0/77
QJ1842 (Similarity)	+150 °C		500 Cycles	2	0/77
QJ1844 (Similarity)	air to air		500 Cycles	3	0/77
QJ1849 (Similarity)			500 Cycles	3	0/77
QJ1851			500 Cycles	4	0/77
Tomography (CSAM)		J-STD-035	Post Temp Cycle	1	0/11
QJ1842 (Similarity)			Post Precon	2	0/22
QJ1843 (Similarity)			Post Temp Cycle	3	0/11
QJ1844 (Similarity)			Post Precon	4	0/22
QJ1845 (Similarity)			Post Precon	5	0/22
QJ1846 (Similarity)			Post Precon	6	0/22
QJ1848 (Similarity)			Post Precon	7	0/11
QJ1849 (Similarity)			Post Precon	8	0/22
QJ1850			Post Precon	9	0/11
QJ1851			Post Temp Cycle	9	0/11

**Background Information:**
**Part #:** CX5375

**Rev:** G

**Fab:** Chartered

**Lead Finish:** Pb-free

**Package:** 64LQFP

**Assembly:** STATChipPAC (China)



<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results</u> <u>(Fail/sample)</u>
Autoclave/PPOT	121 °C	JESD22-A102	96 Hours	1	0/77
QJ1844 (Similarity)	15 psig		96 Hours	2	0/77
QJ1847 (Similarity)	100% R.H.		96 Hours	3	0/77
QJ1849 (Similarity)			96 Hours	4	0/77
QJ1851					
Solderability	93 °C steam aging	JESD22-B102	Solderability	1	0/15
QJ1842 (Similarity)	8 Hours		Solderability	2	0/15
QJ1849 (Similarity)	245 °C solder bath		Solderability	3	0/15
QJ1851	5 Seconds				
HTSL (High Temp Storage Life)	150 °C	JESD22-A103	500 Hours	1	0/77
QJ1842 (Similarity)			1000 Hours	1	0/77
QJ1849 (Similarity)			500 Hours	2	0/77
QJ1851			1000 Hours	2	0/77
			500 Hours	3	0/77
			1000 Hours	3	0/77

**Background Information:**

Part #: CX5375                      Rev: G                      Fab: Chartered                      Lead Finish: Pb-free  
Package: 64LQFP                      Assembly: STATChipPAC (China)

**Data Sheet Change Required?**  Yes  No

If Yes, briefly explain:

**Software Change Required?**  Yes  No

If Yes, briefly explain:

**Customer Acknowledgement and Agreement**

**Acknowledged and Agreed as of the Date written below:**

Customer Company \_\_\_\_\_  
Name:


Customer Contact \_\_\_\_\_  
Name:  
Title: \_\_\_\_\_

Signature: \_\_\_\_\_

Date:

Customer Agreed       Customer Reject       Not Applicable

Customer Comments:

	Title: <b>CUSTOMER PROCESS CHANGE NOTIFICATION FORM</b>		
	Digitally Signed By: <b>Cirrus Logic - Customer Quality</b> <small>Digitally signed by Cirrus Logic - Customer Quality DN: cn=Cirrus Logic - Customer Quality, c=US, ou=Cirrus Logic Austin, email=customer_quality@cirrus.com Reason: All signatures on file Date: 2010.10.13 10:29:51 -05'00'</small>	Doc No: 4-QUAL-00017	Rev: D

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